


SECTION A-A
SCALE 20 : 1

Notes: (Unless Otherwise Specified).

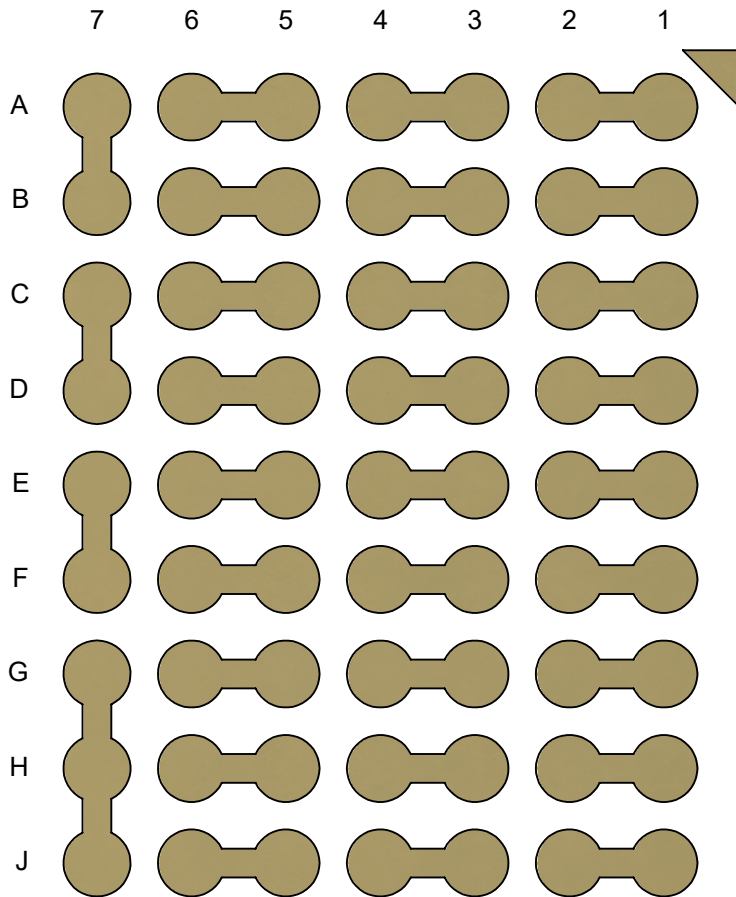
1. ALL DIMENSIONS ARE IN MM.
2. SOLDER BALL: SAC305 (Sn96.5/Ag3.0/Cu0.5).
3. BALL DIAMETER (BEFORE REFLOW): 0.30mm.
4. SOLDER MASK DEFINED PAD OPENING 0.254mm (10mil).
5. PAD Cu DIAMETER: 0.355mm (14mil).
6. SUBSTRATE MATERIAL: BT HL-832NS.
7. MOLDING COMPOUND: EMC G770H.
8. DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA63T.5C-DC0907D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

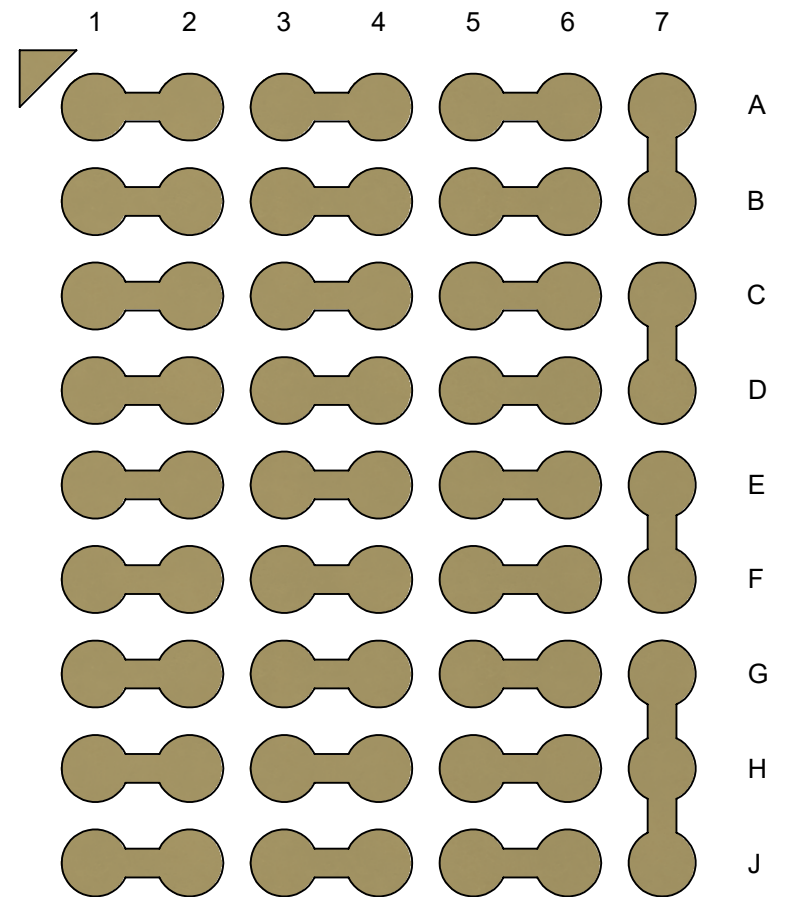
APPROVALS	DATE				
DRAWN T. Au	7/6/2022				
ENG M. Hart	7/6/2022	TITLE		BGA63T.5C-DC0907D 63 BALL P = 0.5mm	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		20:1	A	559072	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

DAISY CHAIN PATTERN

BALL VIEW



BOTTOM SIDE VIEWED FROM TOP



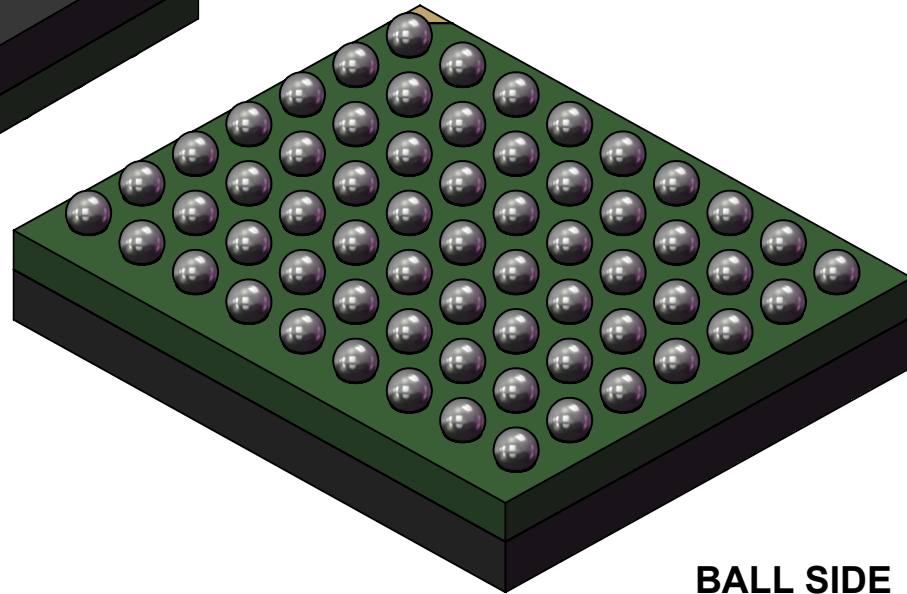
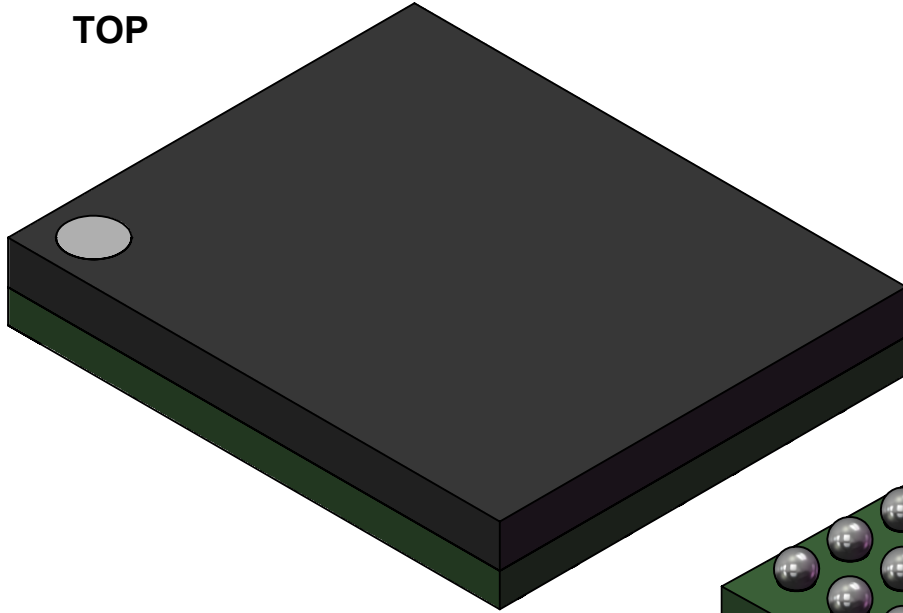
Notes:

1. PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2. PCB Cu BALL PAD DIAMETER: 0.355mm (14mil).
3. PCB DAISY CHAIN TRACING LINE WIDTH: 0.15mm (6mil).

TopLine[®]			
TITLE		BGA63T.5C-DC0907D 63 BALL P = 0.5mm	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	559072	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BALL SIDE

TopLine®

TITLE BGA63T.5C-DC0907D
63 BALL P = 0.5mm

SCALE 20:1	SIZE A	DRAWING NO. 559072	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3